

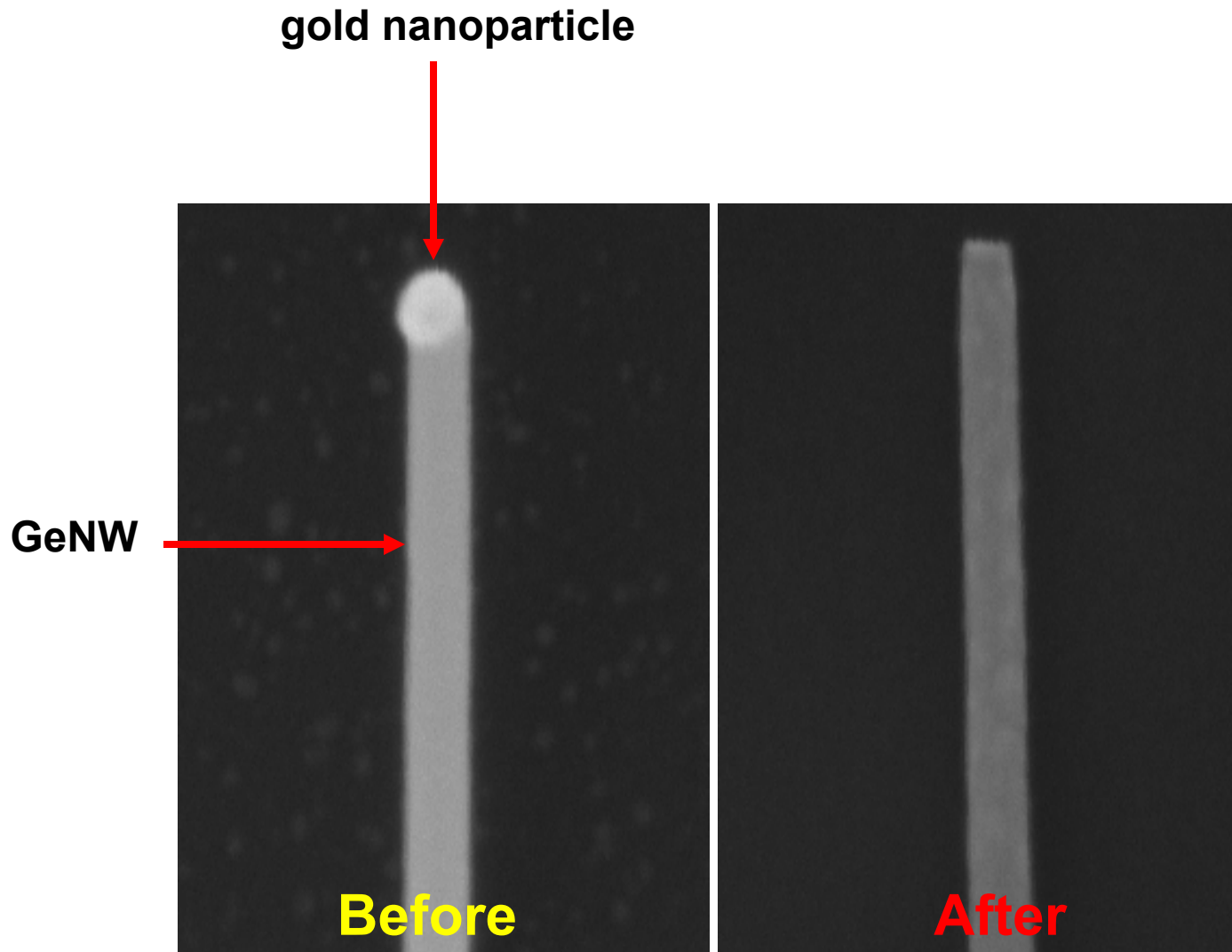
Non-destructive gold removal from germanium nanowire samples

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Outline

- **introduction**
- GeNW growth from gold nanoparticles
- effect of gold in germanium and silicon processing
- gold removal procedure
- chemical characterization of GeNW surfaces before and after gold removal
- effectiveness of the gold removal procedure
- conclusion



- Non-destructive gold removal from the tips of GeNWs
- May be useful for planar Si and Ge surfaces

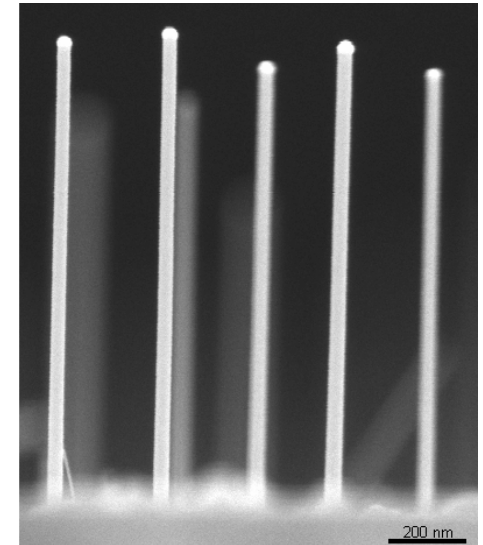
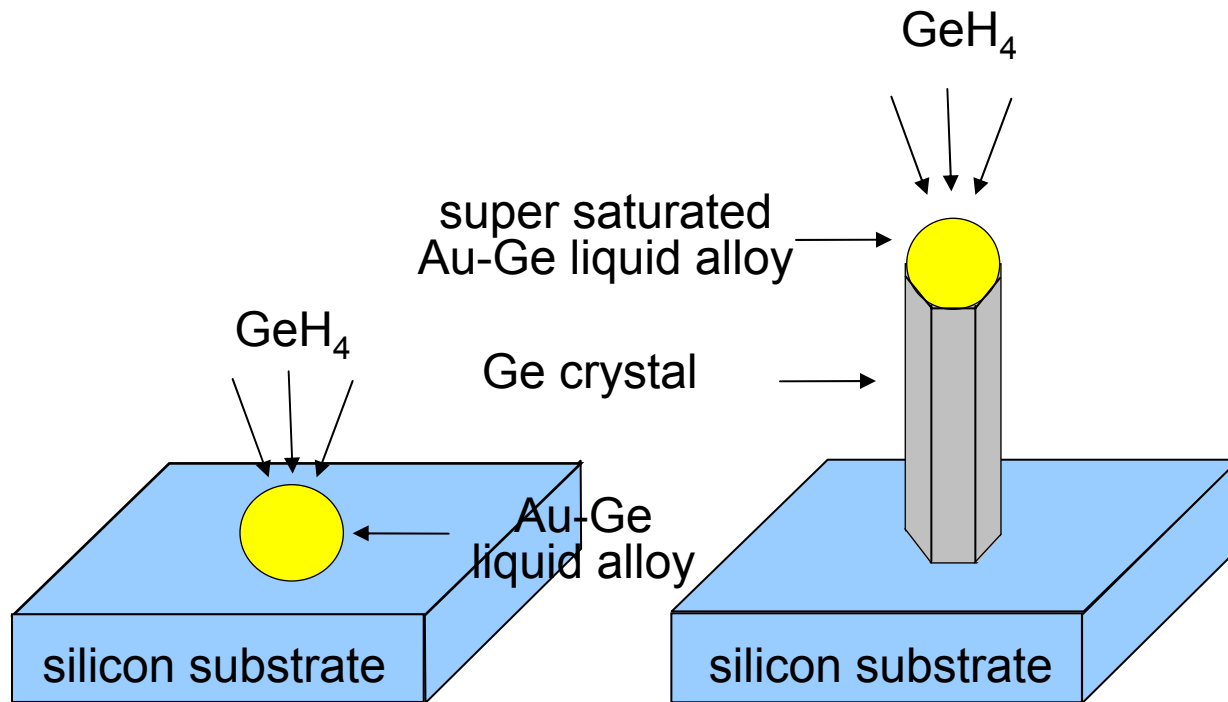
Environmental impact of GeNW electronic materials

- GeNW in-situ growth reduces process waste of expensive bulk materials
- single crystal growth at lower processing temperature
- unknown semiconductor manufacturing process integration of gold catalyzed GeNWs

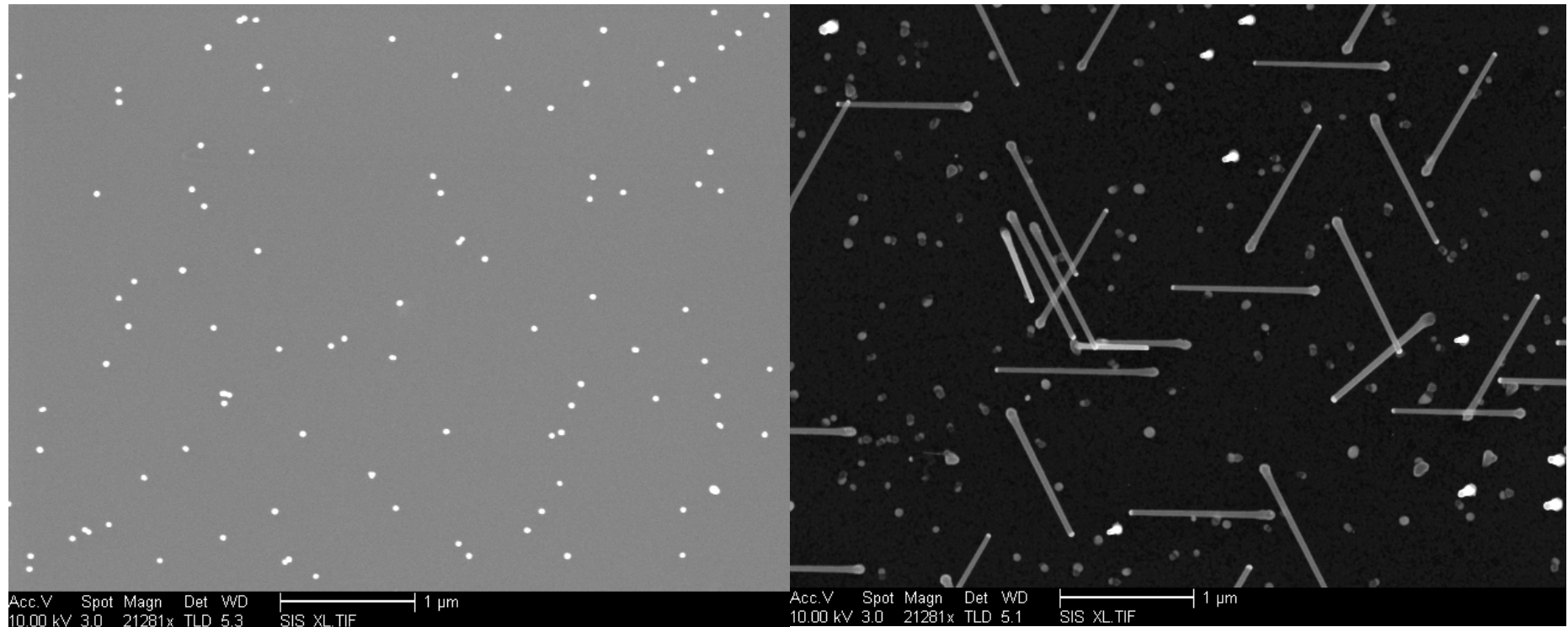
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Gold catalyzed crystal growth from precursor gas

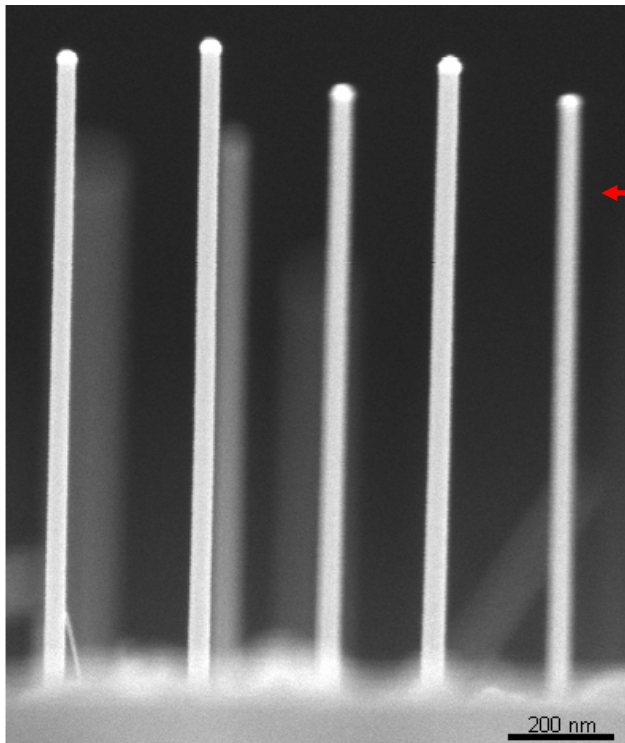


Epitaxial Growth of GeNW from gold nanoparticles on Si <111>

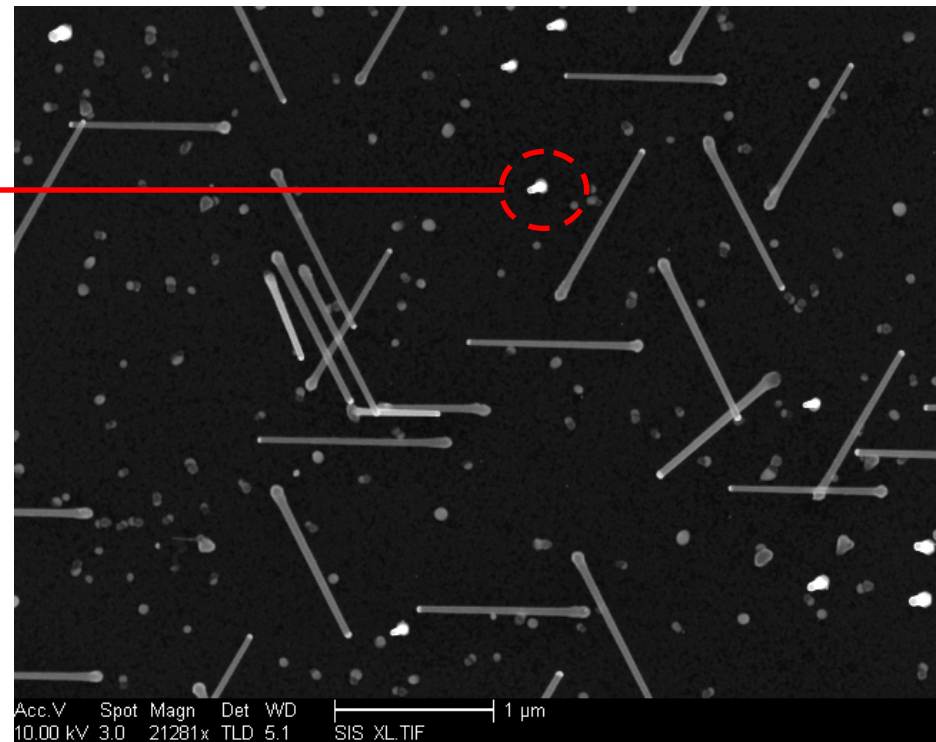


GeNW grown by heating linker free 40 nm gold colloids to 400°C for 2 minutes followed by 280° C for 18 minutes with 0.430 Torr GeH₄(g) and 29.6 Torr H₂ (g).

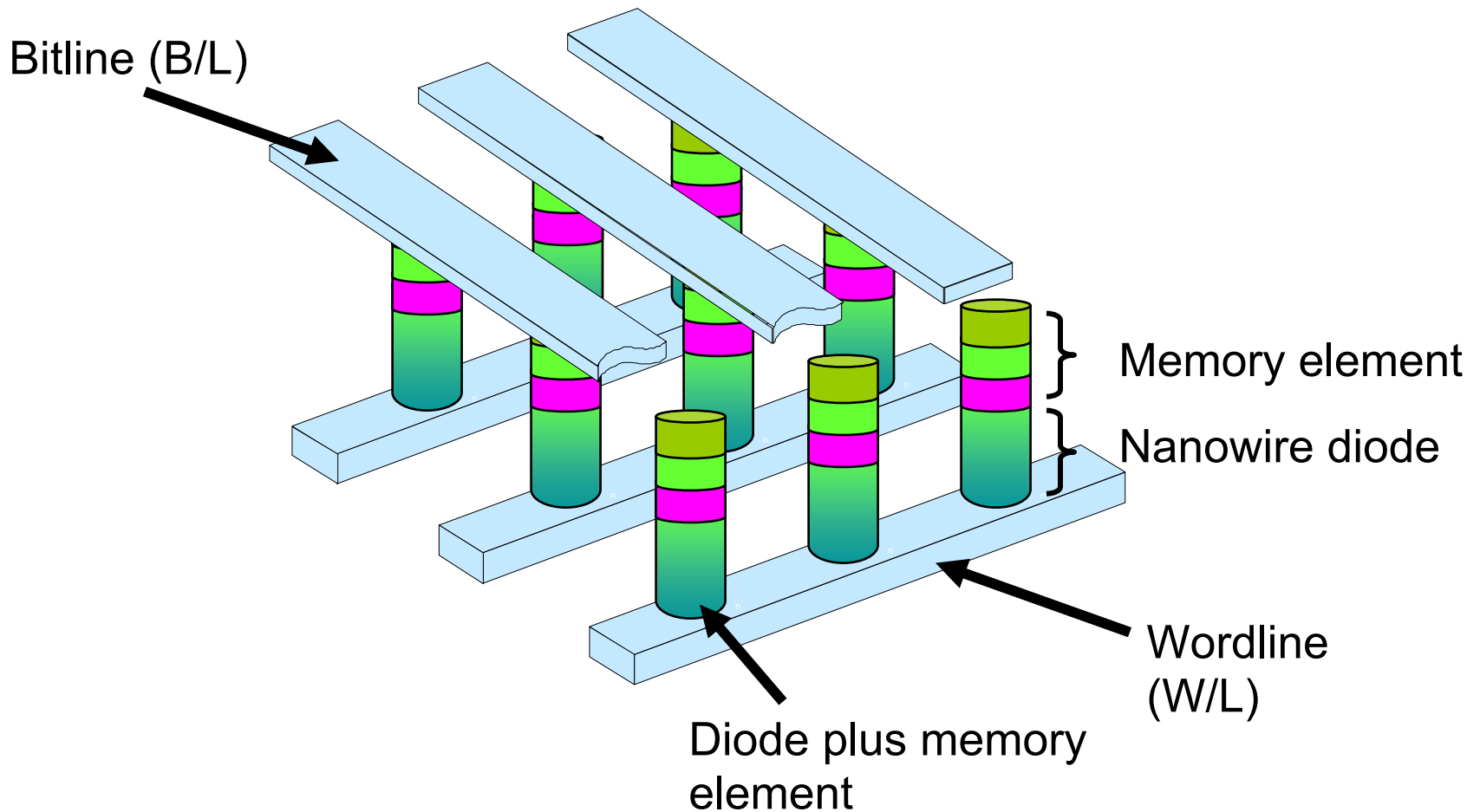
Epitaxial Growth of GeNW from gold nanoparticles on Si $\langle 111 \rangle$



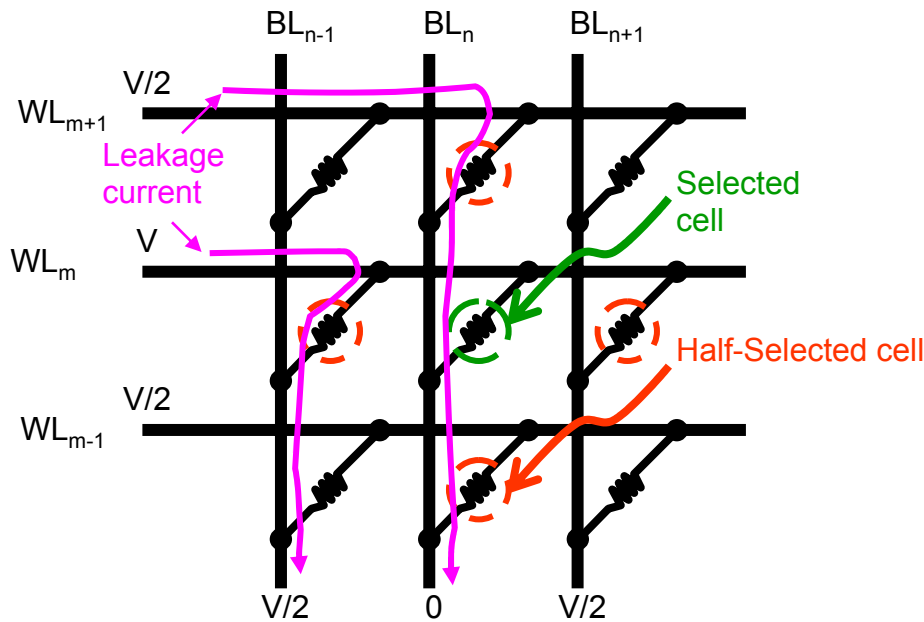
$\langle 111 \rangle$



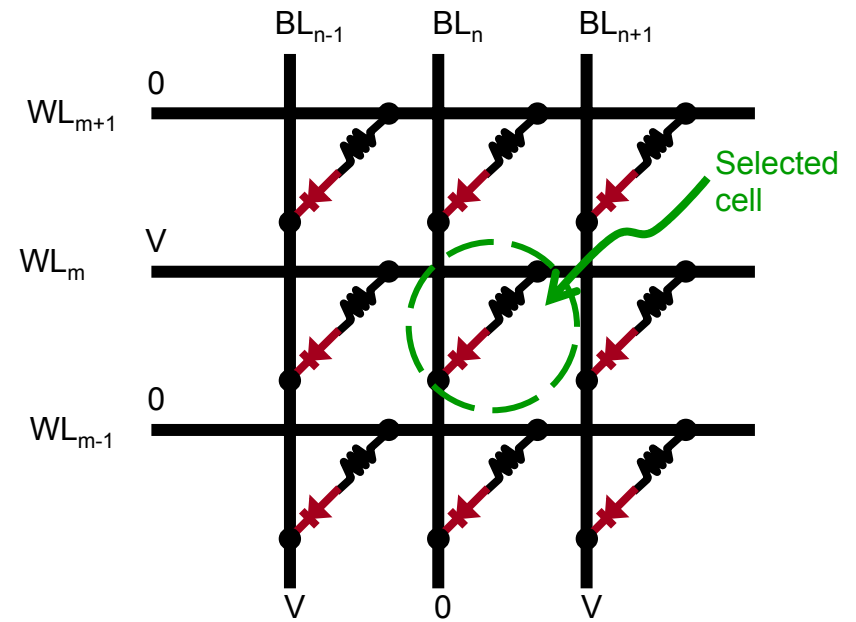
High Density Cross-Point Memory with GeNW Diode



Cross-Point Memory Cell Selection



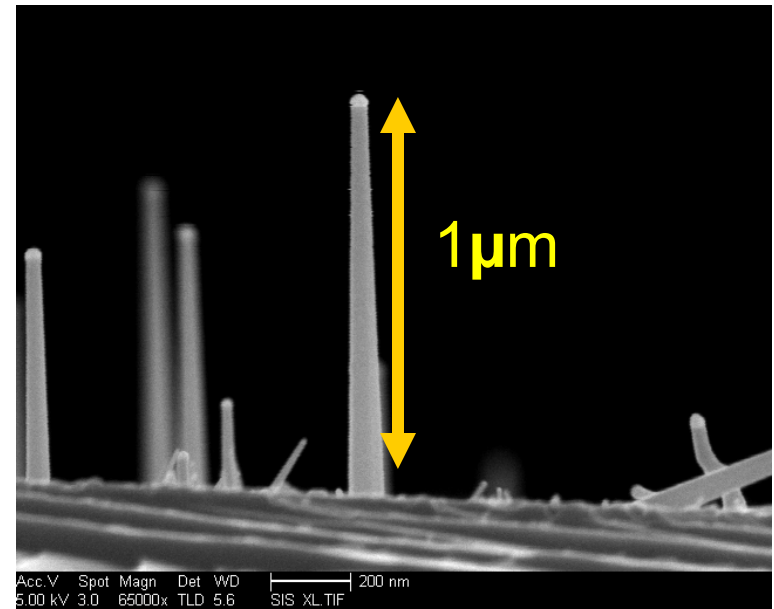
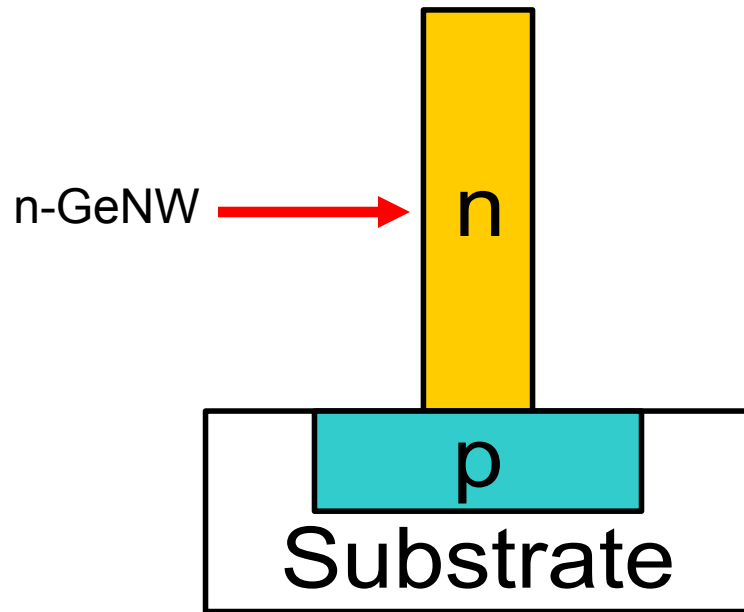
Without Diode



With Diode

GeNW diode

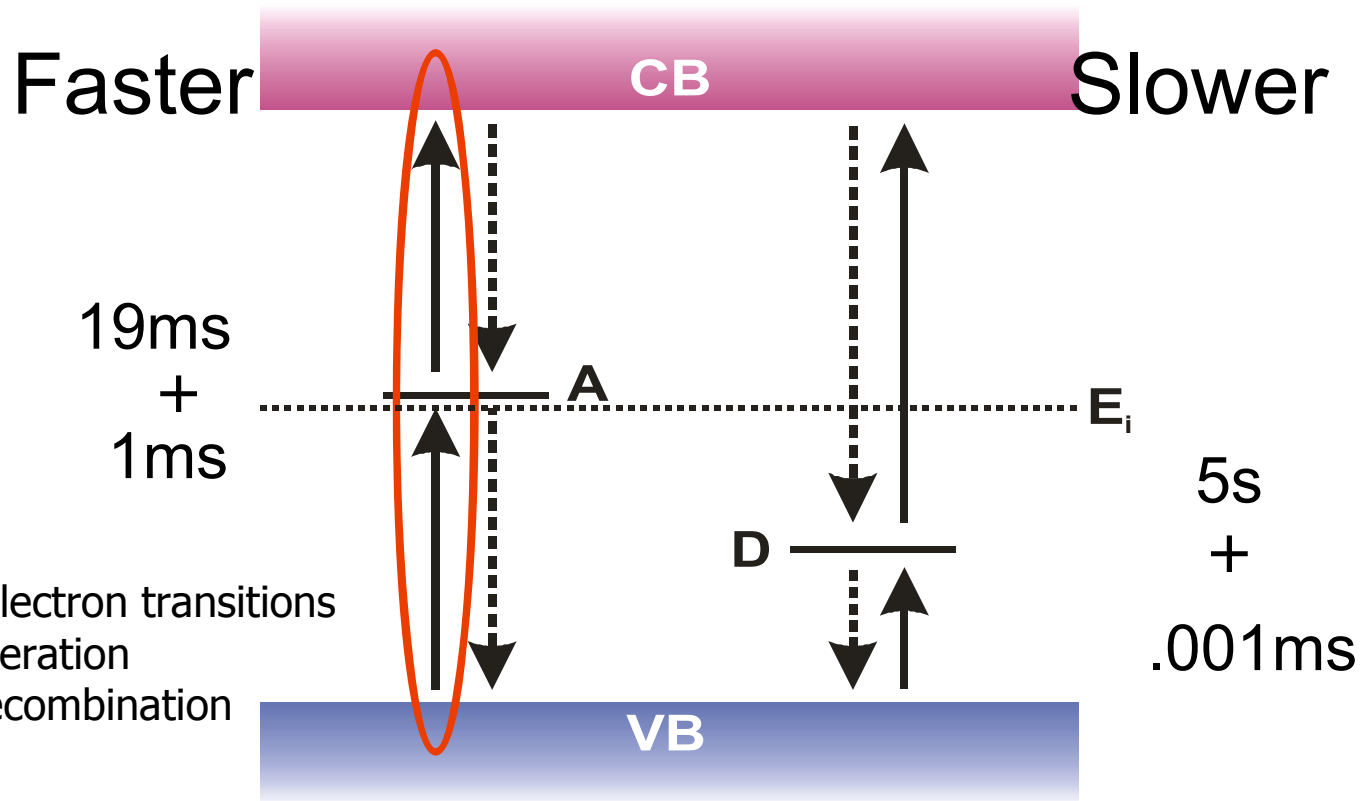
- In-situ phosphorus-doped Ge nanowire standing on p-type Si(111) substrate.
- wafer level processing
- GST-GeNW diode memory cell has ON/OFF ratio ≈ 100



Outline

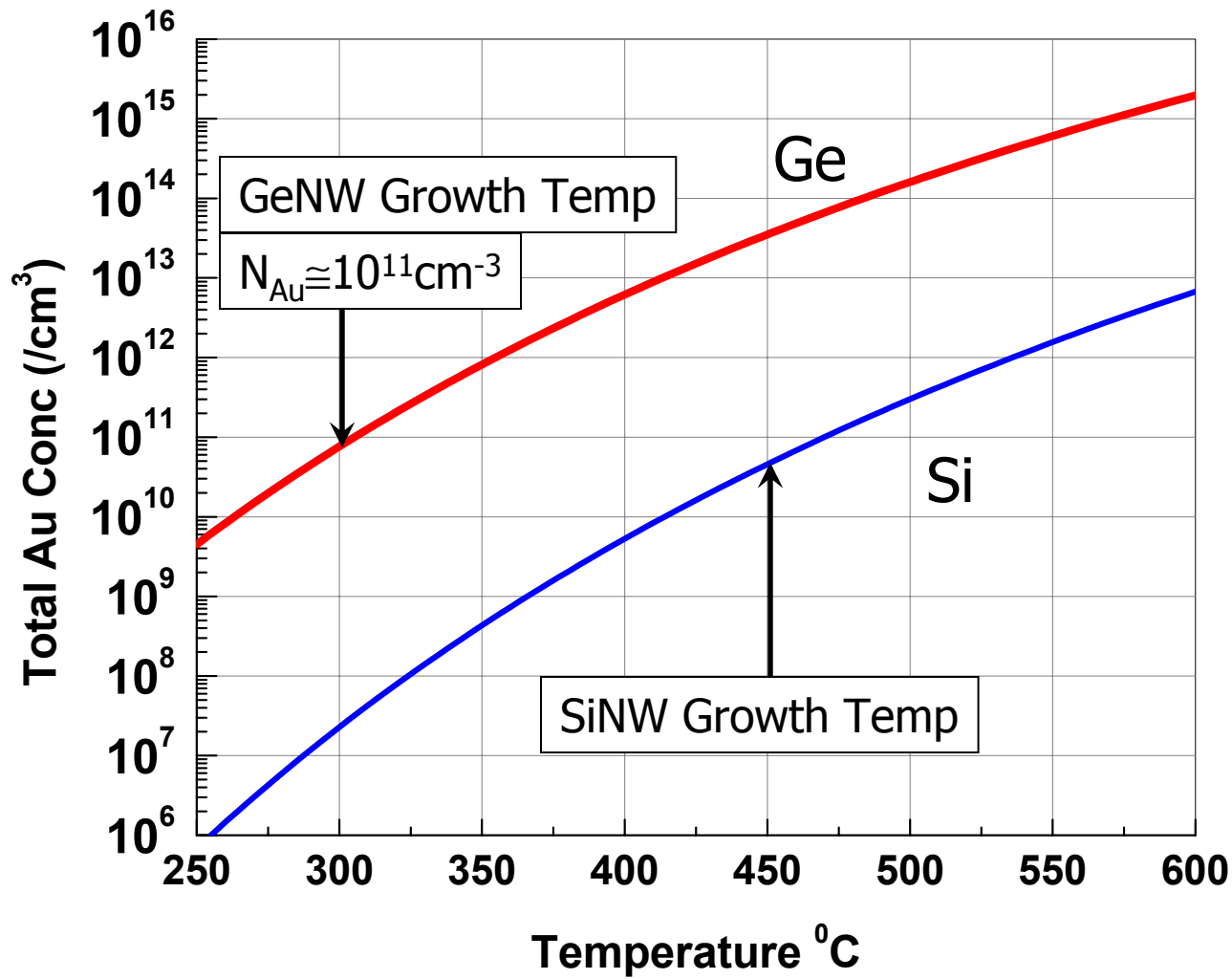
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Recombination-Generation Processes in Si



- Gold introduces midgap states into the silicon and germanium bandgaps increasing the rates of electron-hole recombination and thermal generation
- Level closest to midgap is most efficient for recombination-generation processes

Gold Solubility in Si and Ge

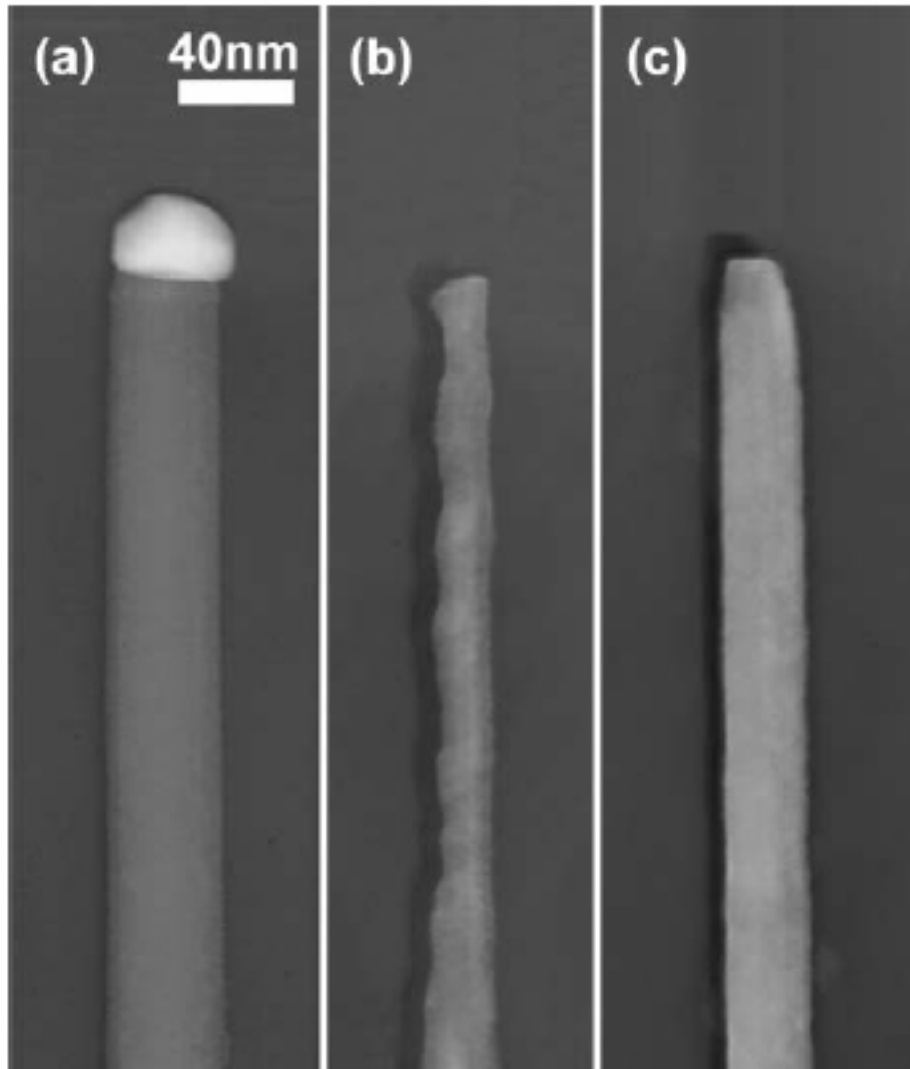


- Ge: Bracht, H., Stolwijk, N.A., Mehrer, H.: Phys. Rev. B 43 (1991) 14465.
- Si: Boit, C., Lau, F., Sittig, R.: Appl. Phys. A 50 (1990) 197.

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Gold removal from GeNW samples



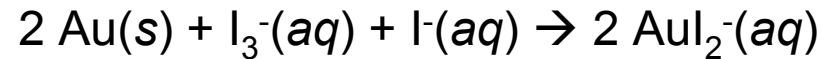
a) as-grown GeNW

b) gold removed GeNW with triiodide (aq)

c) gold removed GeNW with triiodide-HCl (aq)

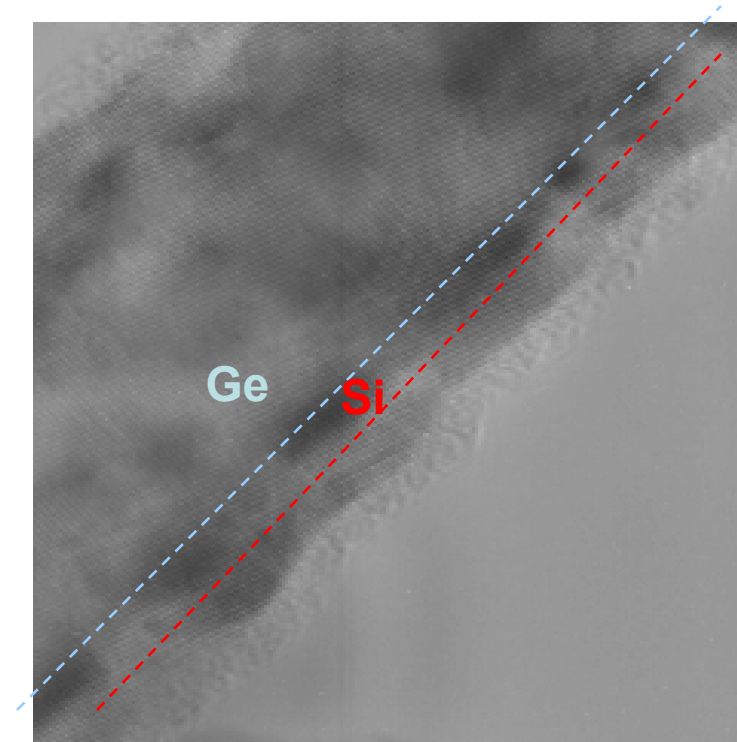
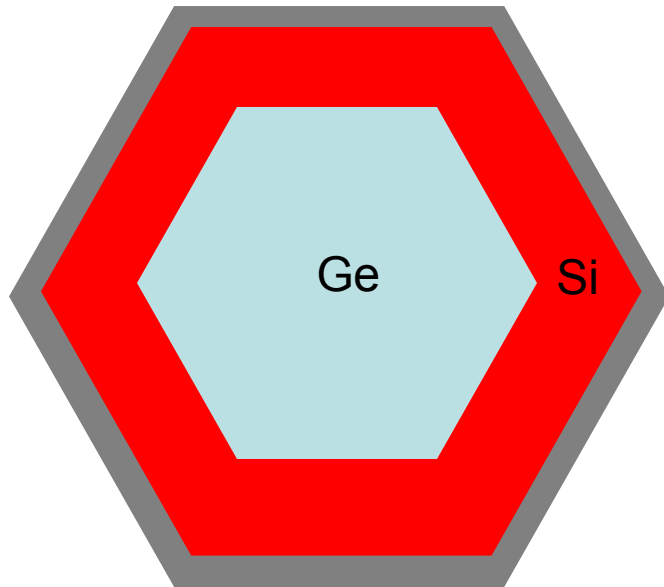
Chemistry of gold removal process

- The overall chemical reaction for the gold removal is expected to be:



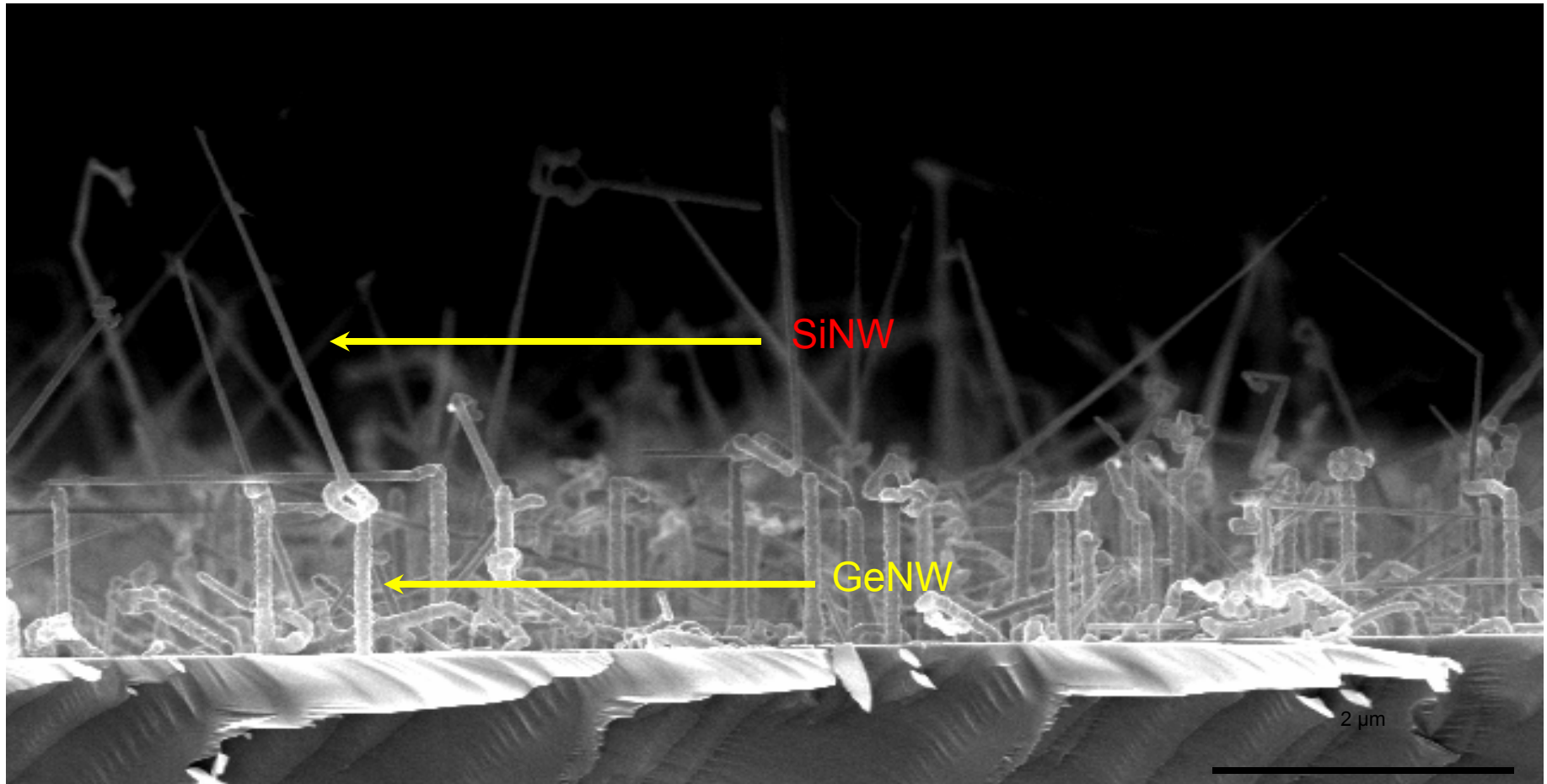
- triiodide etch concentration 1.2% I₂, 30% KI (Transene)
- HCl(aq) prevents GeNW surface oxidation and leaves the GeNW surface Cl terminated

Ge/Si core-shell nanowires



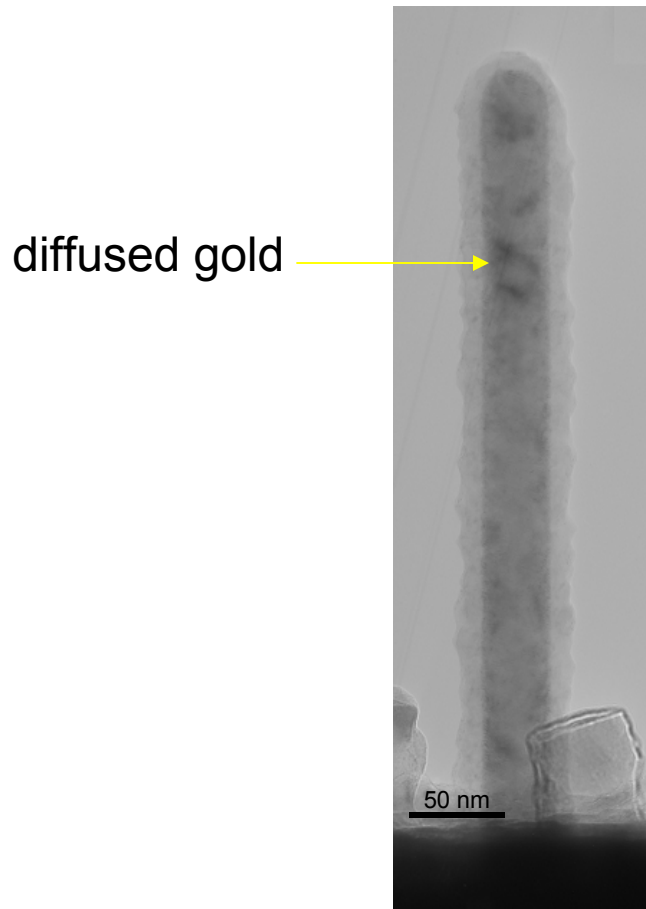
- Ge core because carrier mobilities are higher than in Si, for p-type conduction, and constrains carriers within the Ge core
- Si shell because SiO_2 is a stable, high quality surface passivation

Gold tips of GeNWs and residual gold on substrate grow SiNWs



585°C, $P_{\text{tot}} = 5$ Torr (0.35 Torr SiH_4 with H_2 carrier gas)

At $T > 550^\circ\text{C}$ for a crystalline Si shell, gold diffuses into nanowire structure

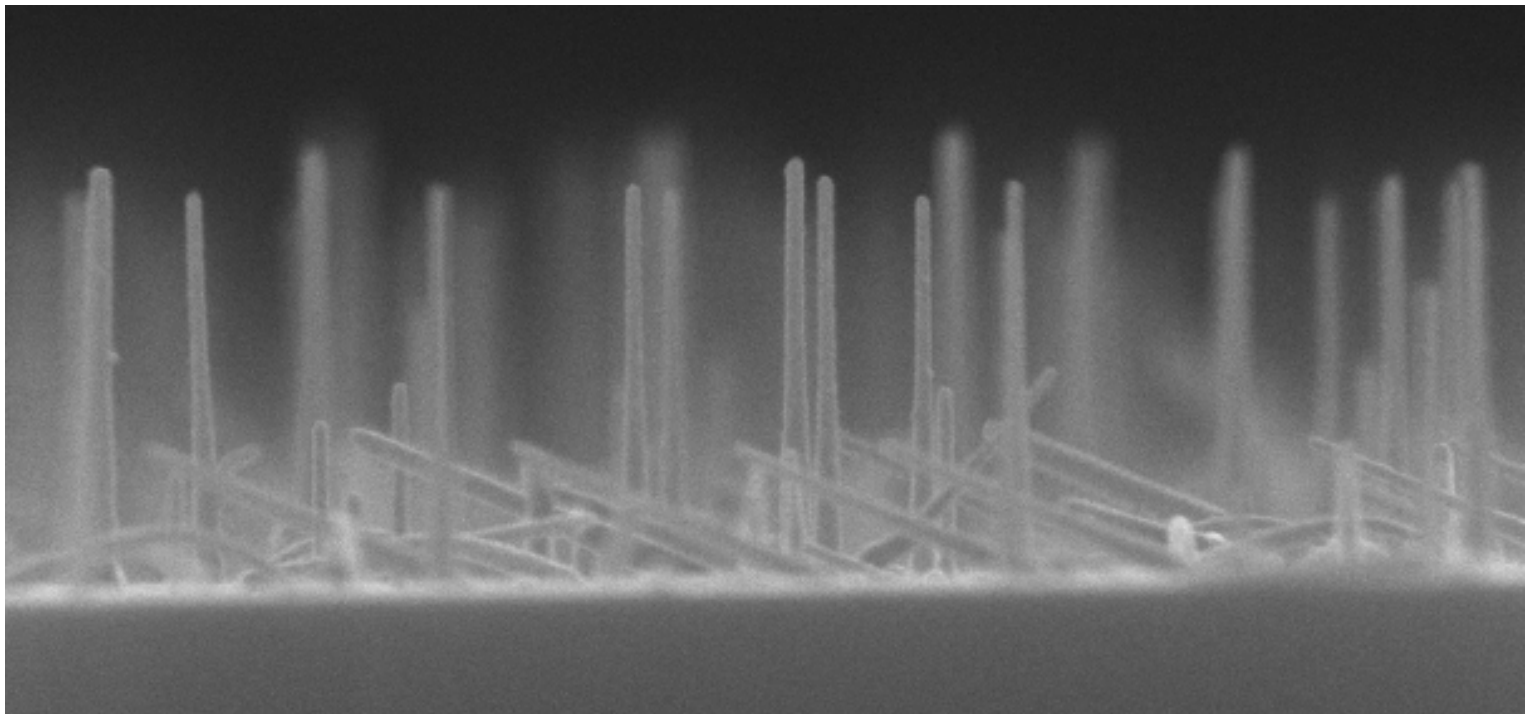


$T > 550^\circ\text{C}$ is need for crystalline Si shell deposition

585°C , $P_{\text{tot}} = 5 \text{ Torr}$ (0.35 Torr SiH_4 with H_2 carrier gas)

Optimal process for coreshell

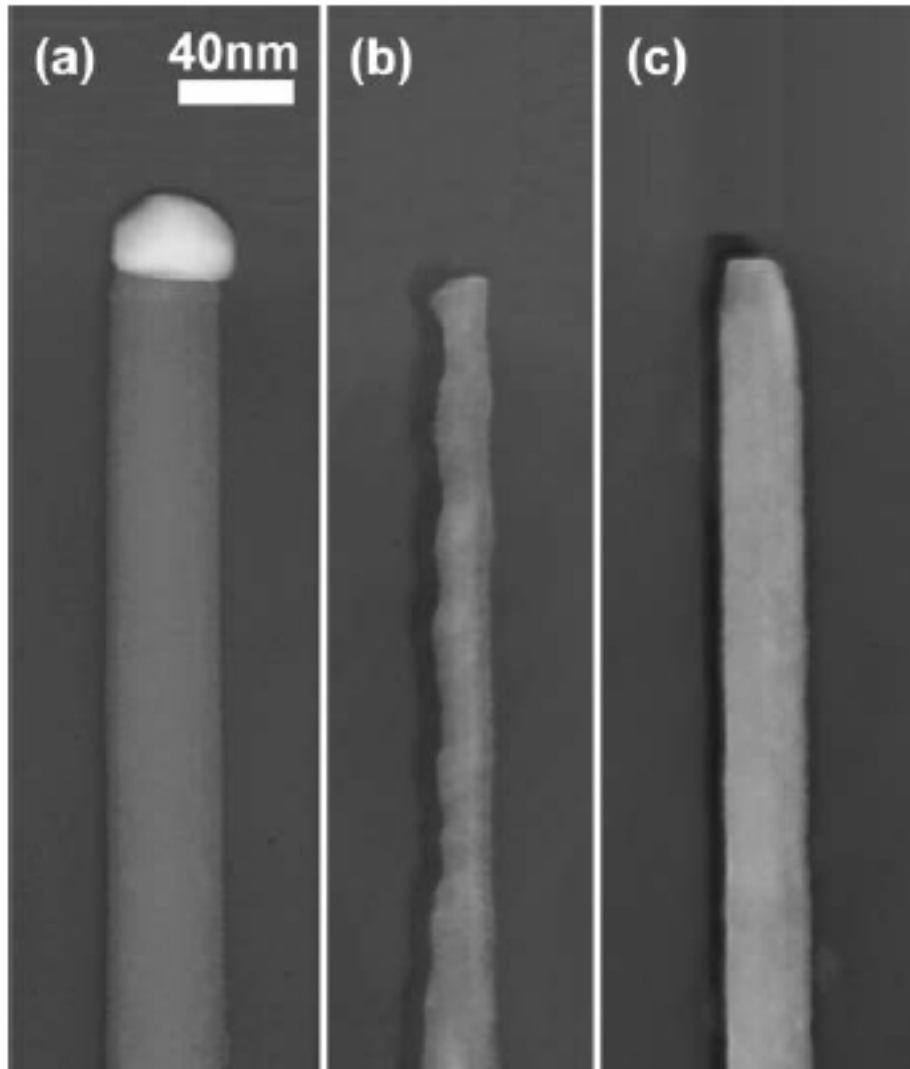
1. Untapered GeNW growth from 20 nm catalysts: 370°C/300°C
2. HCl immersion (5 min), triiodide-HCl gold etch (10s), HCl rinse
3. 10 min anneal @ 600°C in H₂
4. Si deposition: 690°C, P_{tot} = 4.5 Torr, P_{SiH₄} = 0.11 Torr with H₂ carrier gas, 60s



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Gold removal from GeNW samples



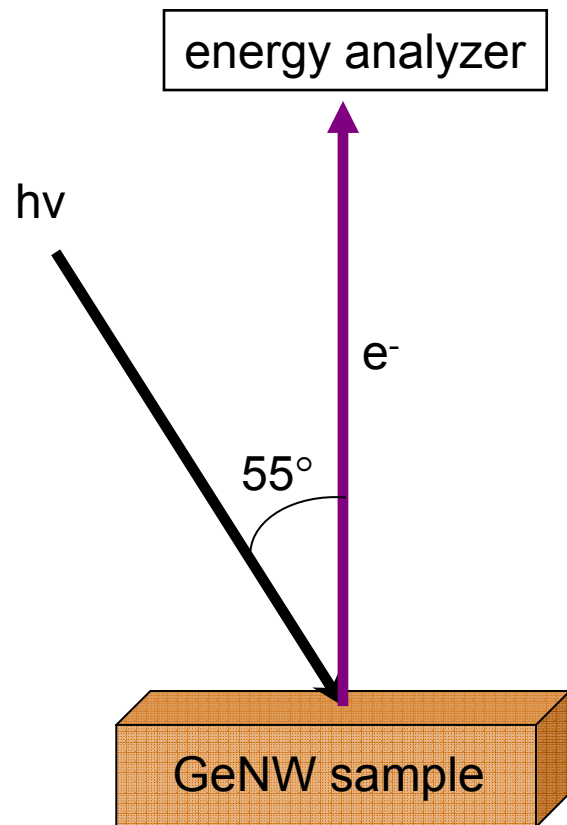
a) as-grown GeNW

b) gold removed GeNW with triiodide (aq)

c) gold removed GeNW with triiodide-HCl (aq)

One needs to characterize the chemical composition of GeNW surfaces for Ge/Si core shell applications

Synchrotron radiation photoemission from GeNW surface

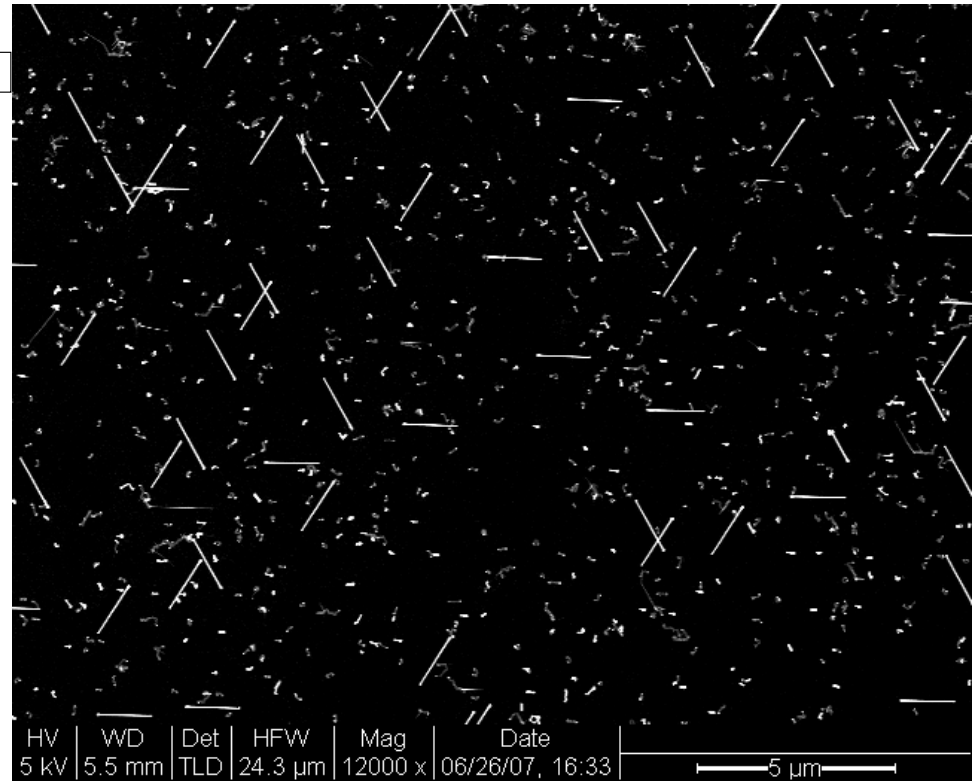
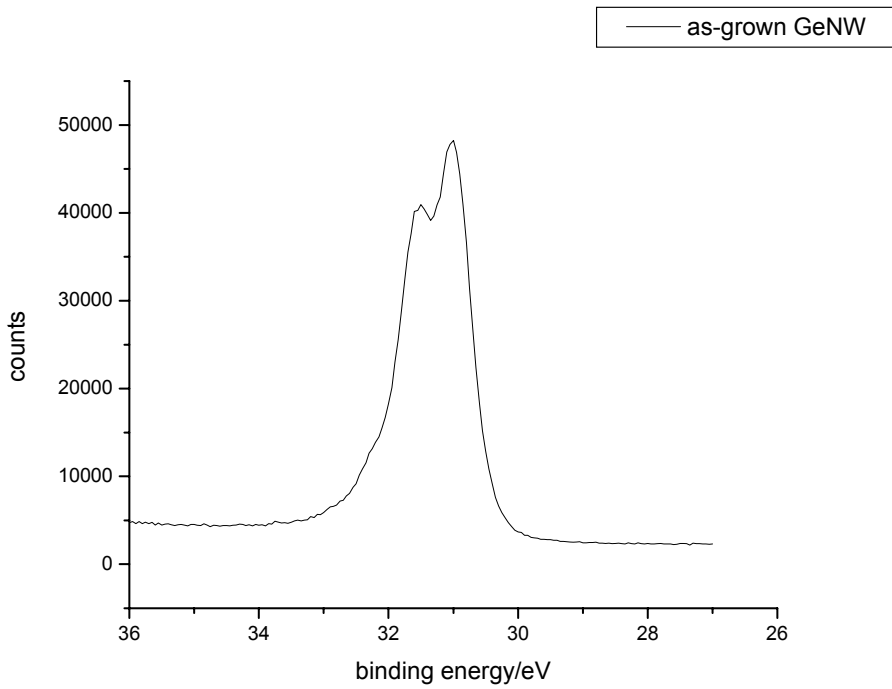


- 10eV to 100eV synchrotron photons were used to study chemical composition of GeNW surfaces

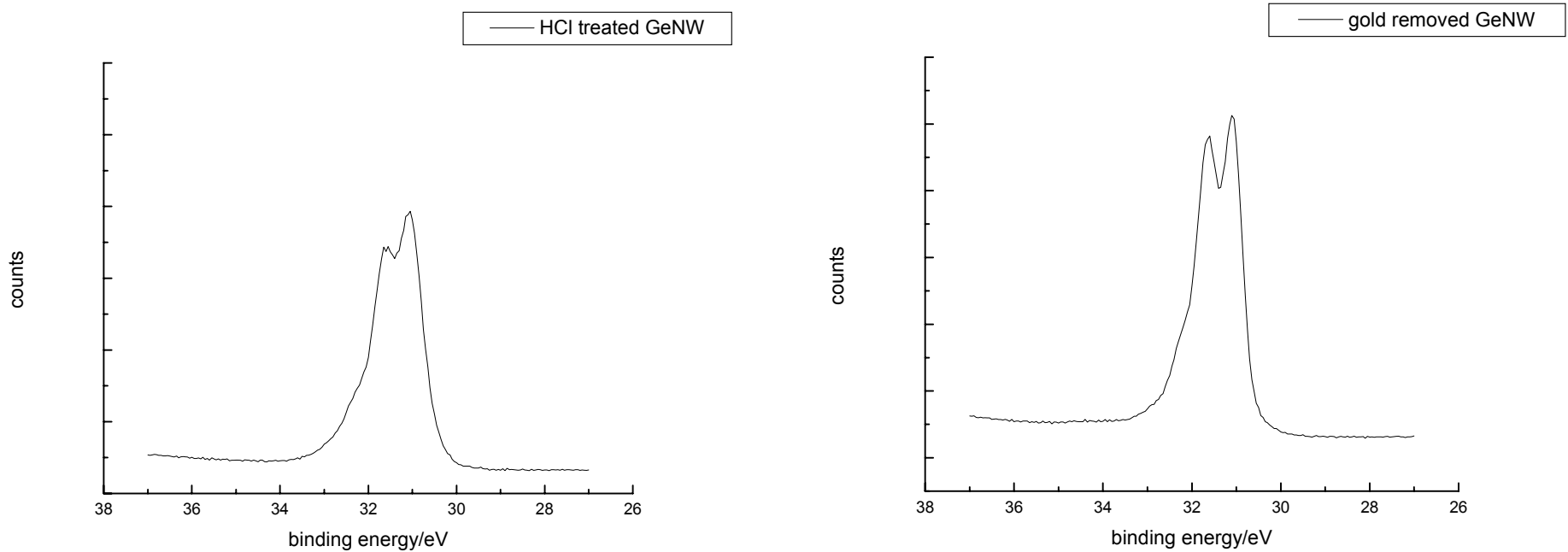
$$E_b = hv - E_k - \Phi_a$$

- Ge3d spectrum used to determine any change in the chemical composition of GeNW surface

Ge3d spectrum of as-grown GeNW



Ge3d spectrum of HCl treated then triiodide-HCl treated GeNW sample

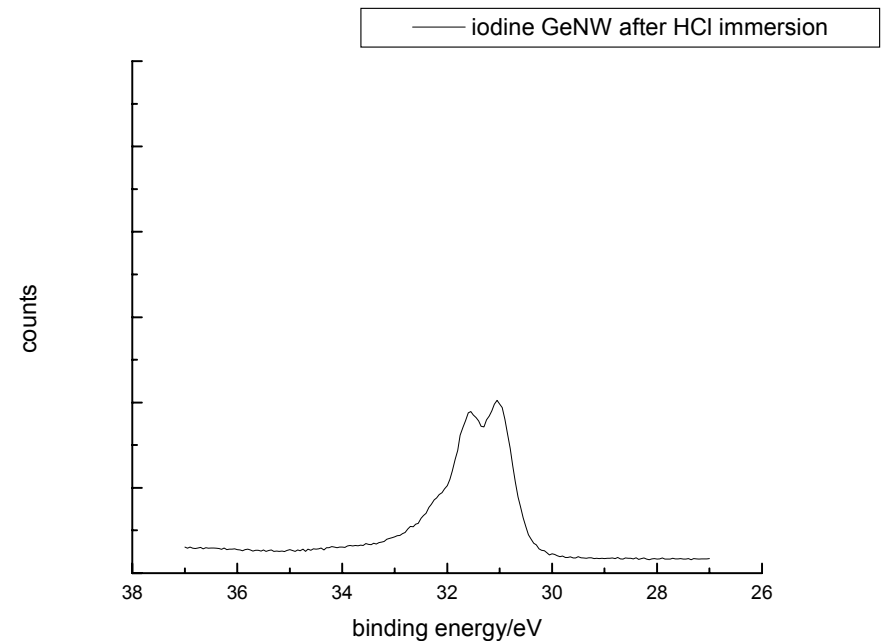
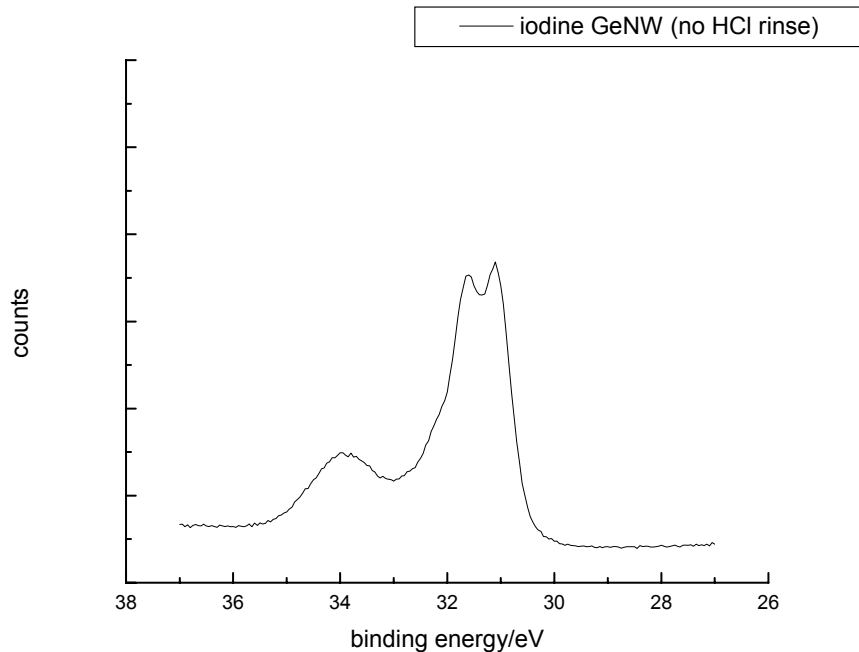


HCl (aq) prevents the oxidation of GeNW surfaces

Adhikari, H., McIntyre, P.C., et.al. "Photoemission studies of the passivation of germanium nanowires" Applied Physics Letters 87(26):263109

Hanrath, T., and B.A. Korgel. "Chemical surface passivation of Ge nanowires" Journal of the American Chemical Society 126(47) 15466-15472

Ge3d spectrum of triiodide treated then HCl treated GeNW samples

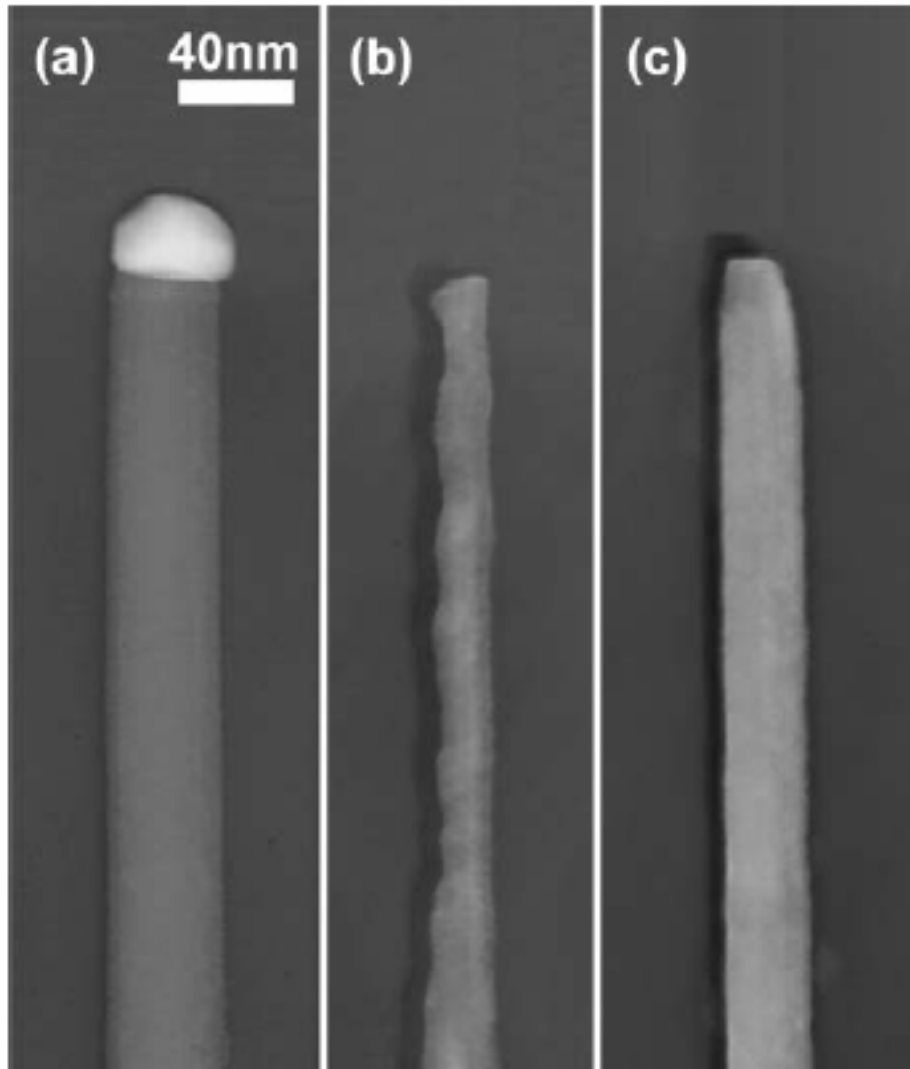


HCl (aq) renders the GeNW surface Cl terminated

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Gold removal from GeNW samples



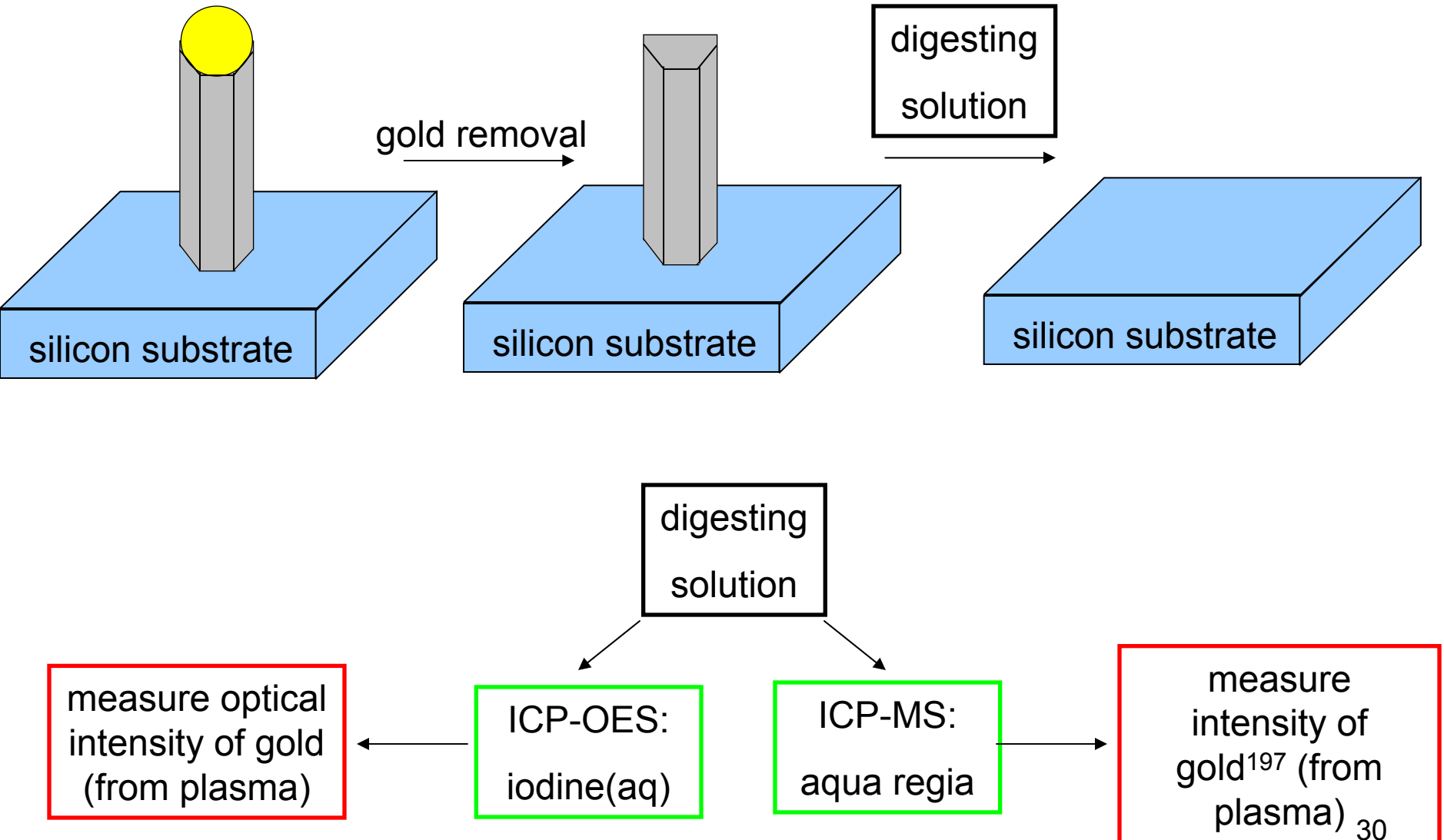
a) as-grown GeNW

b) gold removed GeNW with triiodide (aq)

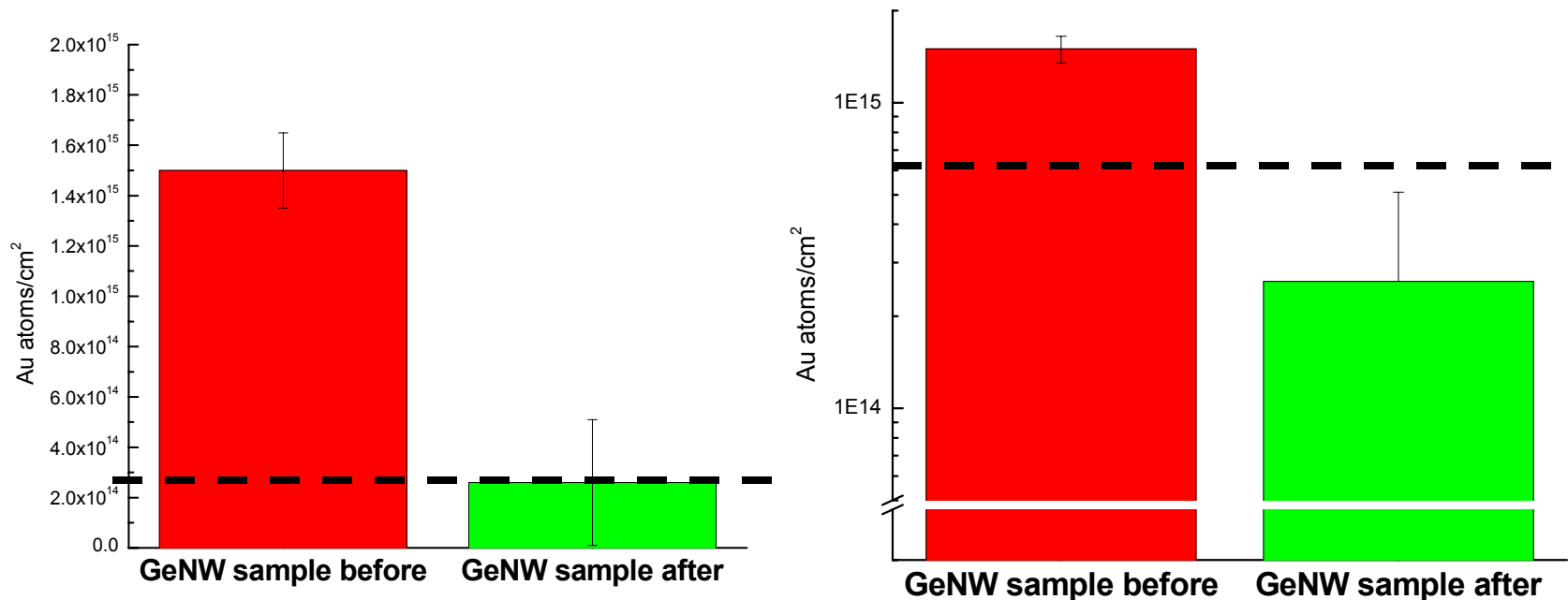
c) gold removed GeNW with triiodide-HCl (aq)

One needs to show that gold atoms have been removed to 1×10^{10} atoms/cm² (ITRS 2006)

ICP OES and ICP MS method

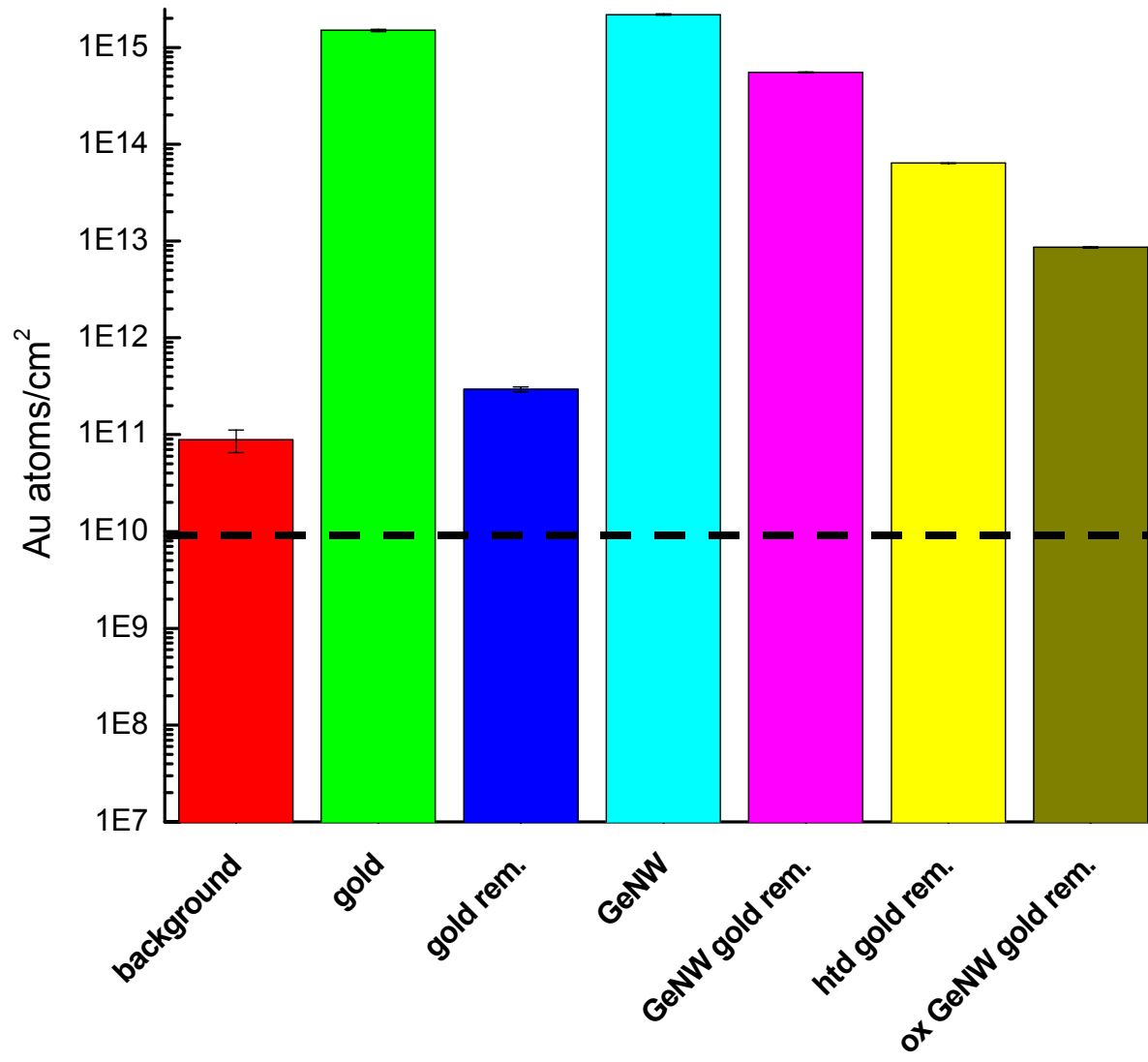


ICP-OES measurement of extent of gold removal



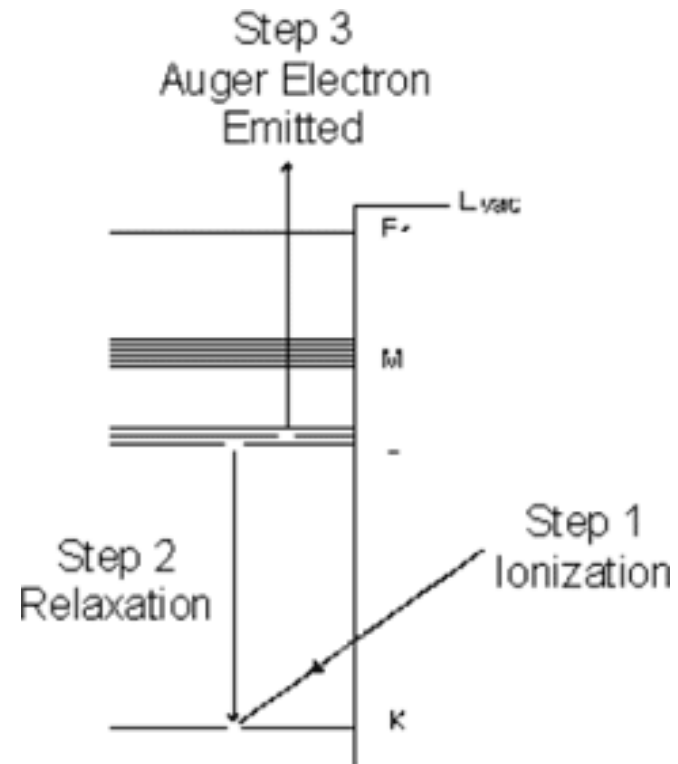
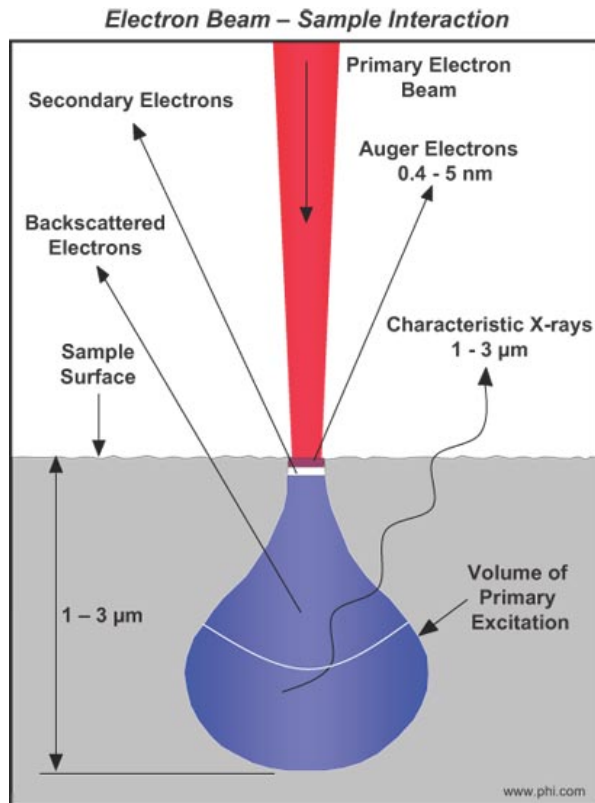
ICP-OES detection limit (— —) too high to measure trace levels of gold

ICP-MS measurement of extent of gold removal

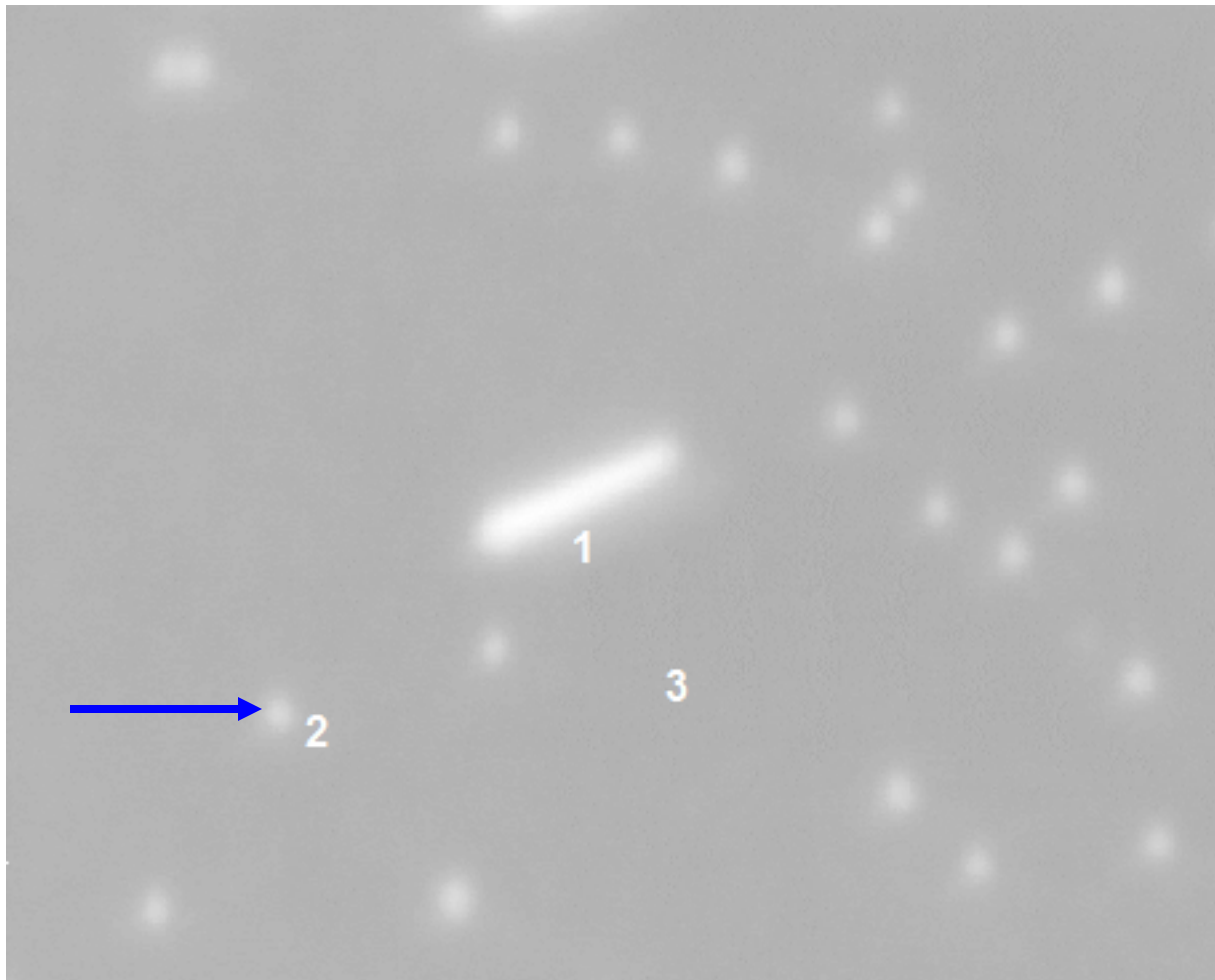


Source of residual gold?

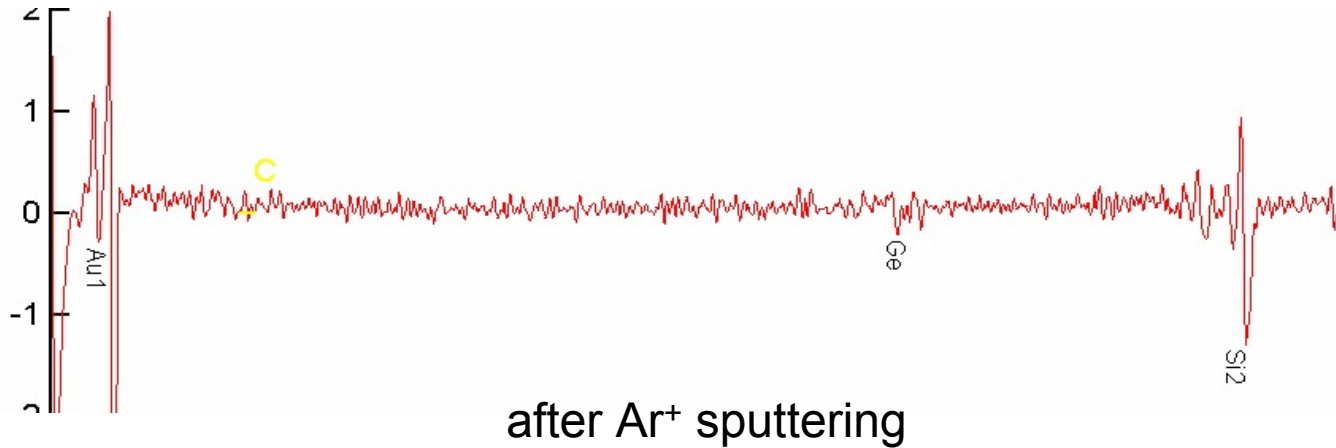
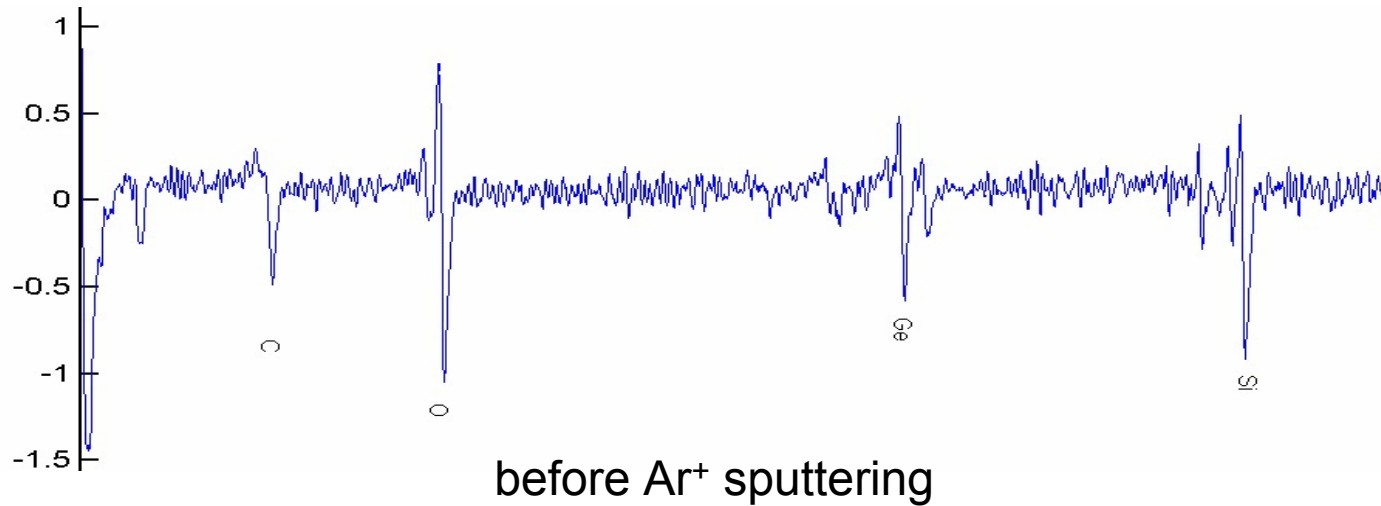
- used Auger electron spectroscopy to perform microanalysis at specific sample features



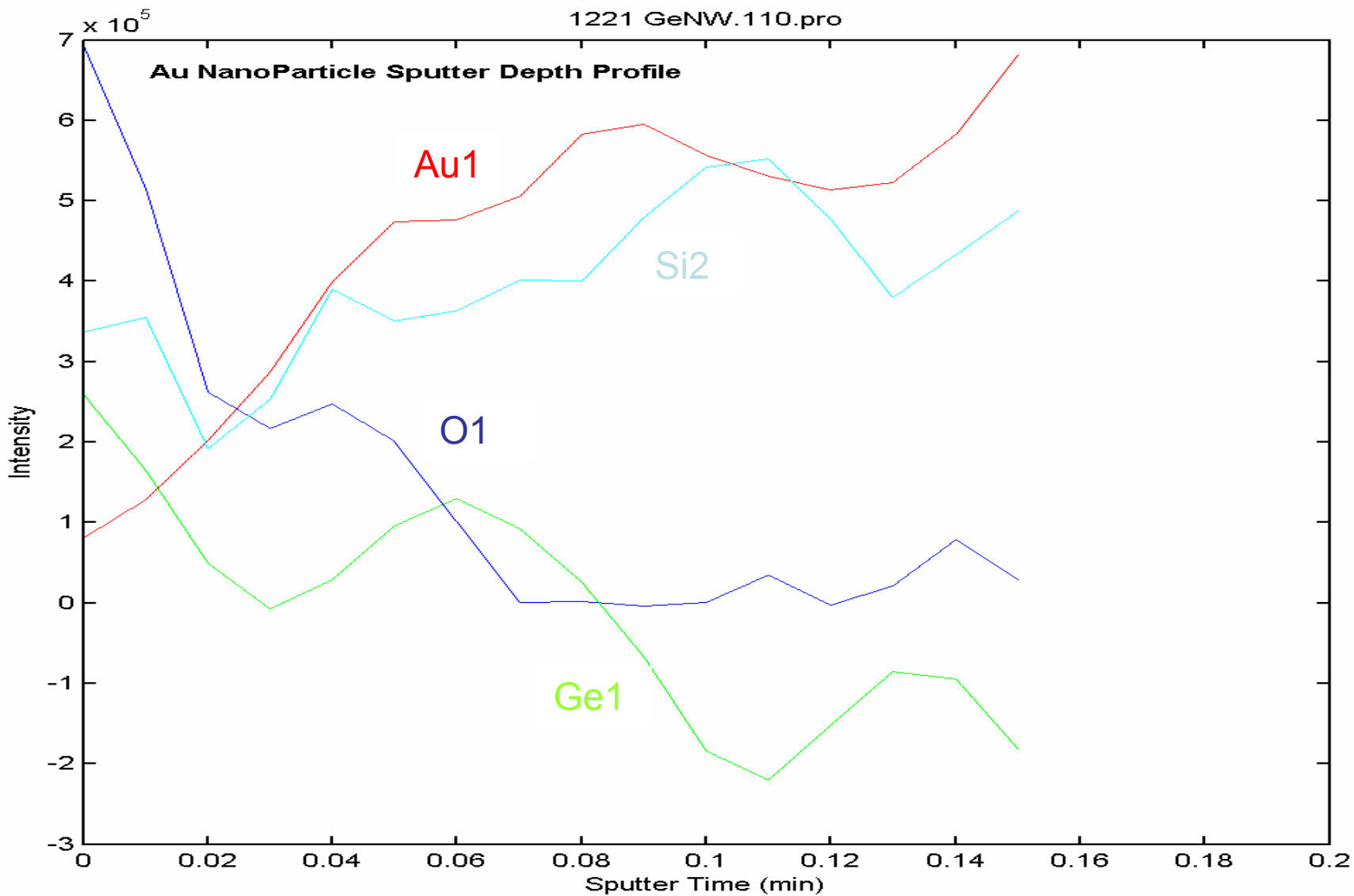
Secondary electron image of gold particles and Ge Wire



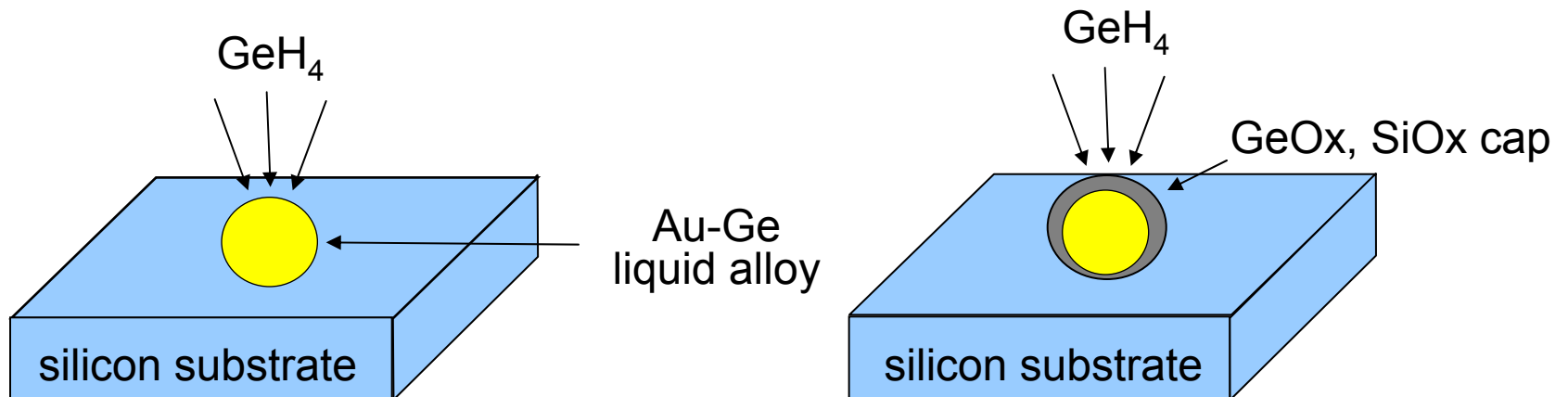
Auger electron spectrum at point 2



Sputter Depth Profile of Au nanoParticle



Capped gold nanoparticle reduces yield and effectiveness of gold removal?



Environmental impact of GeNW electronic materials

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- single crystal growth at lower processing temperature
- unknown semiconductor manufacturing process integration of gold catalyzed GeNWs

Acknowledgements

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- ICP-MS: Rob Franks, University of California-Santa Cruz Marine Analytical Lab
- AES: Chuck Hitzman, Stanford Nanocharacterization Laboratory
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